

Features

- 2 channel, bidirectional buffer
- I²C-bus and SMBus compatible
- Operating supply voltage range of 2.3 V to 3.6 V
- Active HIGH repeater enable input
- Open-drain input/outputs
- Lock-up free operation
- Supports arbitration and clock stretching across the repeater
- Accommodates Standard-mode and Fast-mode I²C-bus devices and multiple masters
- Powered-off high-impedance I²C-bus pins
- 5.5 V tolerant I²C-bus and enable pins
- 0 Hz to 400 kHz clock frequency (the maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater)
- ESD protection exceeds 4kV HBM per JESD22-A114
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.
<https://www.diodes.com/quality/product-definitions/>
- Package: MSOP-8, SOIC-8 and DFN2x3-8L

Description

The PI6ULS5V9515A is a CMOS integrated circuit intended for I²C bus and SMBus systems applications. The device contains two identical bidirectional open-drain buffer circuits that enable I²C and similar bus systems to be extended without degradation of system performance.

The PI6ULS5V9515A enables the system designer to isolate two halves of a bus for both voltage and capacitance, accommodating more I²C devices or longer trace length. It also permits extension of the I²C-bus by providing bidirectional buffering for both the data (SDA) and the clock (SCL) lines, thus allowing two buses of 400 pF to be connected in an I²C application.

The PI6ULS5V9515A has an EN pin to turn the drivers on and off. This can be used to isolate a badly behaved slave on power-up until after the system power-up reset. It should never change state during an I²C-bus operation because disabling during a bus operation will hang the bus and enabling part way through a bus cycle could confuse the I²C-bus parts being enabled. The enable pin should only change state when the global bus and the repeater port are in an idle state to prevent system failures.

The output low levels for sides are approximately 0.5 V, but the input voltage of each internal buffer must be 70 mV lower (0.43V) or even more lower. When the output internally is driven low the low is not recognized as a low by the input. This prevents a lockup condition from occurring when the input low condition is released.

Two or more PI6ULS5V9515A devices can't be used in series. The PI6ULS5V9515A design does not allow this configuration. Since there is no direction pin, slightly different valid low-voltage levels are used to avoid lockup conditions between the input and the output of each repeater. A valid low applied at the input of a PI6ULS5V9515A will be propagated as a buffered low with a slightly higher value on the output. When this buffered low is applied to another PI6ULS5V9515A-type device in series, the second device does not recognize it as a valid low and will not propagate it as a buffered low again.

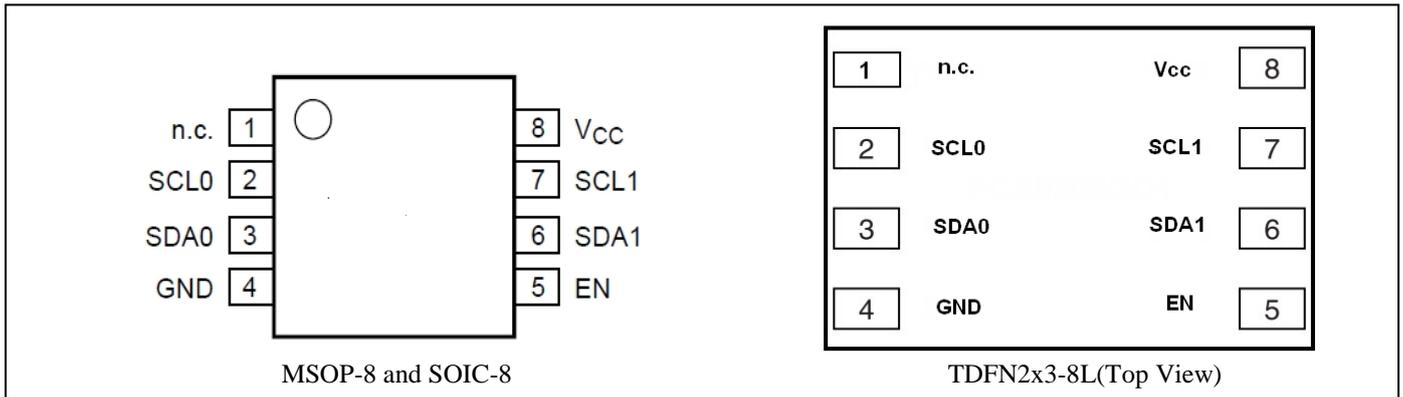
The device contains a power-up control circuit that sets an internal latch to prevent the output circuits from becoming active until V_{CC} is at a valid level (V_{CC} = 2.3 V).

As with the standard I²C system, pull-up resistors are required to provide the logic-high levels on the buffered bus. The PI6ULS5V9515A has standard open-collector configuration of the I²C bus. The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. The device is designed to work with Standard mode and Fast mode I²C devices in addition to SMBus devices. Standard mode I²C devices only specify 3mA in a generic I²C system, where Standard mode devices and multiple masters are possible. Under certain conditions, higher termination currents can be used.

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Configuration



Pin Description

Pin#	Name	Description
1	n.c.	Not connected
2	SCL0	serial clock port 0 bus
3	SDA0	serial data port 0 bus
4	GND	supply ground (0 V)
5	EN	active HIGH repeater enable input
6	SDA1	serial data port 1 bus
7	SCL1	serial clock port 1 bus
8	V _{CC}	supply voltage (2.3 V to 3.6 V)

Block Diagram

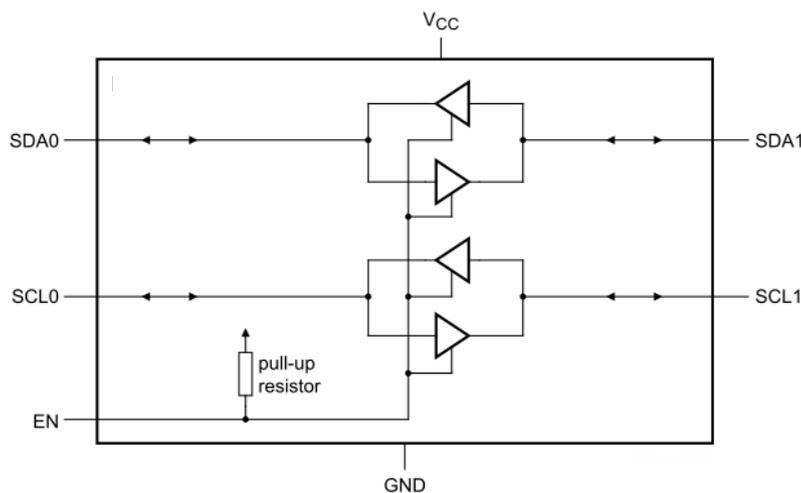


Figure 1: Block Diagram

EN	Function
H	SCL0 = SCL1; SDA0 = SDA1;
L	disabled

Maximum Ratings

Storage Temperature.....	-55°C to +125°C
DC Input Voltage.....	-0.5V to +6.0V
Control Input Voltage(EN).....	-0.5V to +6.0V
Total Power Dissipation.....	100mA
Input/Output Current (portA&B).....	50mA
Input Current (EN, V _{CC(A)} , V _{CC(B)} , GND).....	50mA
ESD: HBM Mode.....	4000V

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Operation Conditions

V_{CC} = 2.3 V to 3.6 V; GND = 0 V; T_{amb} = -40 °C to +85 °C; unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{CC}	supply voltage port	-	2.3	-	3.6	V
I _{CCH}	HIGH-level supply current	both channels HIGH;; SDAn = SCLn = V _{CC} V _{CC} = 2.7 V	-	0.5	5	mA
		both channels HIGH;; SDAn = SCLn = V _{CC} V _{CC} = 3.6 V	-	0.5	5	mA
I _{CCL}	LOW-level supply current	both channels LOW; V _{CC} = 2.7 V; one SDA and one SCL = GND; other SDA and SCL open	-	1.6	5	mA
		both channels LOW; V _{CC} = 3.6 V; one SDA and one SCL = GND; other SDA and SCL open	-	1.7	5	mA
I _{CCLC}	contention port A supply current	V _{CC} = 2.7V or 3.6V; SDAn = SCLn = GND	-	1.6	5	mA

DC Electrical Characteristics

V_{CC} = 2.7 V to 5.5 V; GND = 0 V; T_{amb} = -40 °C to +85 °C; unless otherwise specified

Parameter	Description	Test Conditions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Unit
Input and output SDAn and SCLn						
V _{IH}	HIGH-level input voltage	-	0.7V _{CC}	-	5.5	V
V _{IL} ⁽¹⁾	LOW-level input voltage	-	-0.5	-	+0.3V _{CC}	
V _{ILc}	Contention LOW-level input voltage	-	-0.5	0.4	-	
V _{IK}	Input clamping voltage	I _I = -18 mA	-	-	-1.2	V
I _{LI}	Input leakage current	V _I = 3.6 V	-	-	±1	µA
I _{IL}	LOW-level input current	V _{CC} =2.3-2.7V ; SDA, SCL; V _I = 0.2 V	-	-	10	µA
		V _{CC} =3.0-3.6V ; SDA, SCL; V _I = 0.2 V	-	-	5	µA
V _{OL}	LOW-level output voltage	I _{OL} = 20 µA or 6 mA	0.47	0.52	0.6	V
V _{OL} -V _{ILc}	Difference between LOW-level output and LOW-level input voltage contention	guaranteed by design	-	70	-	mV
I _{LOH}	HIGH-level output leakage current	V _O = 3.6 V	-	-	10	µA
C _{io}	input/output capacitance	V _I = 3 V or 0 V	-	6	-	pF
Enable						
V _{IH}	HIGH-level input voltage	-	2.0	-	5.5	V
V _{IL}	LOW-level input voltage	-	-0.5	-	+0.8	V
I _{IL}	LOW-level input current	V _I = 0.2 V	-	-10	-30	µA
I _{LI}	Input leakage current	V _I = V _{CC}	-1	-	+1	µA
C _i	Input capacitance	V _I = 3.0 V or 0 V	-	6	-	pF

Notes:

1 V_{IL} specification is for the first LOW level seen by the SDAB/SCLB lines. V_{ILc} is for the second and subsequent LOW levels seen by the SDAn/SCLn lines.

Dynamic Characteristics

GND = 0 V; T_{amb} = -40 °C to +85 °C; unless otherwise specified. ⁽¹⁾⁽²⁾

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{cc} =2.3-2.7V						
t _{PLH}	LOW-to-HIGH propagation delay	-	33	113	190	ns
t _{PHL}	HIGH-to-LOW propagation delay	-	-	82	130	ns
t _{TLH}	LOW-to-HIGH transition time	-	-	148	-	ns
t _{THL}	HIGH-to-LOW transition time	-	-	57	-	ns
t _{SU}	Set-up time	-	100	-	-	ns
t _H	Hold time	-	130	-	-	ns
V _{cc} =3.0-3.6V						
t _{PLH}	LOW-to-HIGH propagation delay	-	33	102	180	ns
t _{PHL}	HIGH-to-LOW propagation delay	-	-	68	120	ns
t _{TLH}	LOW-to-HIGH transition time	-	-	147	-	ns
t _{THL}	HIGH-to-LOW transition time	-	-	58	-	ns
t _{SU}	Set-up time	-	100	-	-	ns
t _H	Hold time	-	100	-	-	ns

Notes:

(1) Typical values taken at V_{CC} = 3.3 V and T_{amb} = 25°C.

(2) Different load resistance and capacitance will alter the RC time constant, thereby changing the propagation delay and transition times.

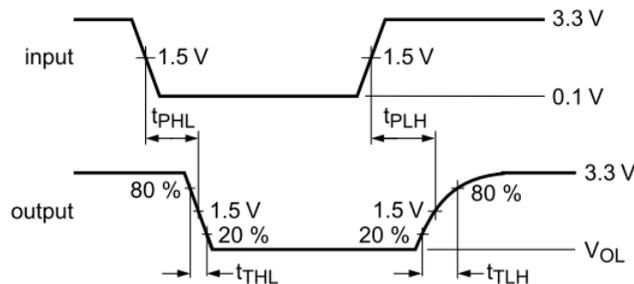
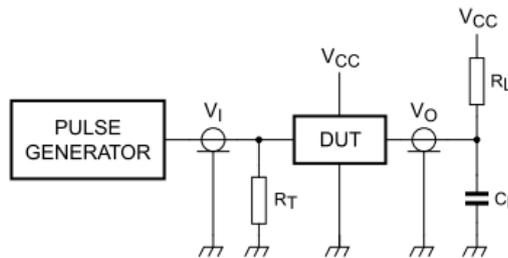


Figure 2: Propagation Delay and Transition Times



R_L = load resistor; 1.35 kΩ

C_L = load capacitance includes jig and probe capacitance; 50 pF

R_T = termination resistance should be equal to Z_o of pulse generators

Figure 3: Test Circuit

Functional Description

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Application Information

A typical application is shown in Figure 4. In this example, the system master is running on a 3.3 V I²C-bus while the slave is connected to a 5V bus. Both buses run at 400 kHz. Master devices can be placed on either bus.

The PI6ULS5V9515A is 5V tolerant, so it does not require any additional circuitry to translate between different bus voltages. When one side of the PI6ULS5V9515A is pulled LOW by a device on the I²C-bus, a CMOS hysteresis type input detects the falling edge and causes the internal driver on the other side to turn on, thus causing the other side to also go LOW. The side driven LOW by the PI6ULS5V9515A will typically be at V_{OL} = 0.5 V.

Figure 5 and Figure 6 show the waveforms that are seen in a typical application. If the bus master in Figure 4 writes to the slave through the PI6ULS5V9515A, Bus 0 has the waveform shown in Figure 5. This looks like a normal I²C transmission until the falling edge of the eighth clock pulse. At that point, the master releases the data line (SDA) while the slave pulls it low through the PI6ULS5V9515A. Because the V_{OL} of the PI6ULS5V9515A typically is around 0.5V, a step in the SDA is seen. After the master has transmitted the ninth clock pulse, the slave releases the data line.

On the Bus 1 side of the PI6ULS5V9515A, the clock and data lines have a positive offset from ground equal to the V_{OL} of the PI6ULS5V9515A. After the eighth clock pulse, the data line is pulled to the V_{OL} of the slave device, which is very close to ground in the example.

It is important to note that any arbitration or clock-stretching events on Bus 1 require that the V_{OL} of the devices on Bus 1 be 70 mV below the V_{OL} of the PI6ULS5V9515A (see V_{OL} - V_{ILC} in Electrical Characteristics) to be recognized by the PI6ULS5V9515A and transmitted to Bus 0.

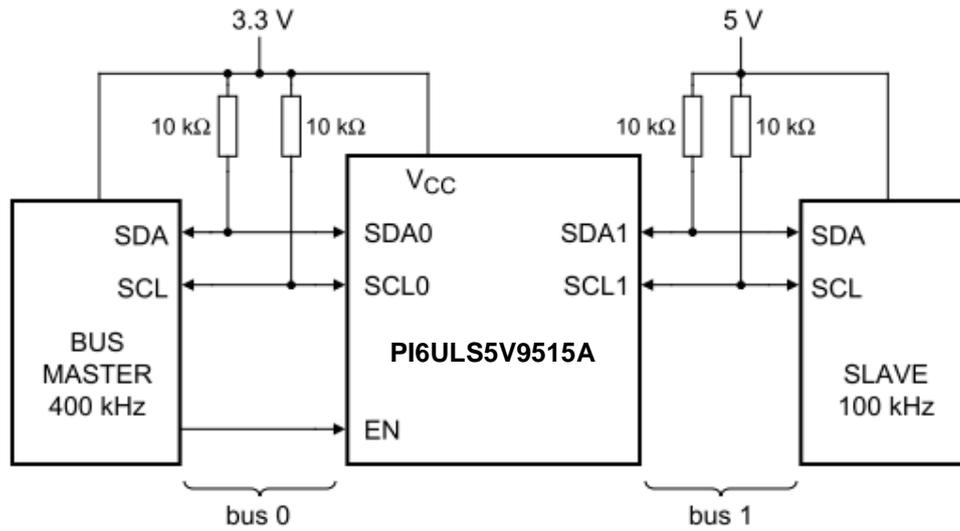


Figure 4: Typical Application

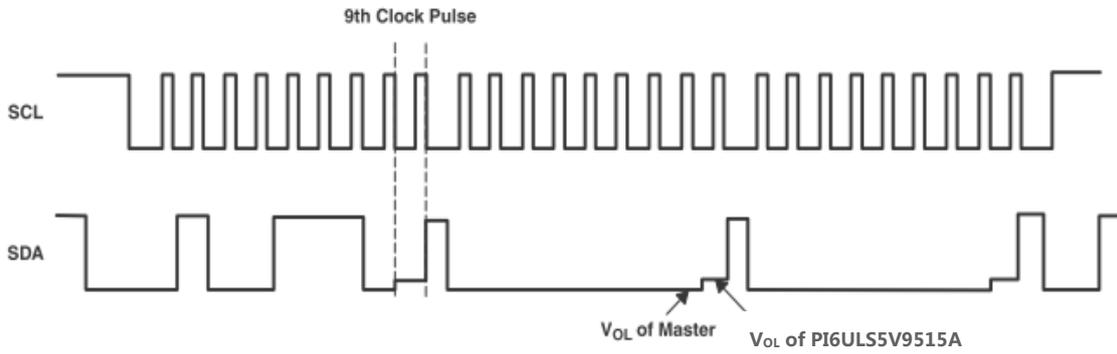


Figure 5: Bus 0 Waveforms

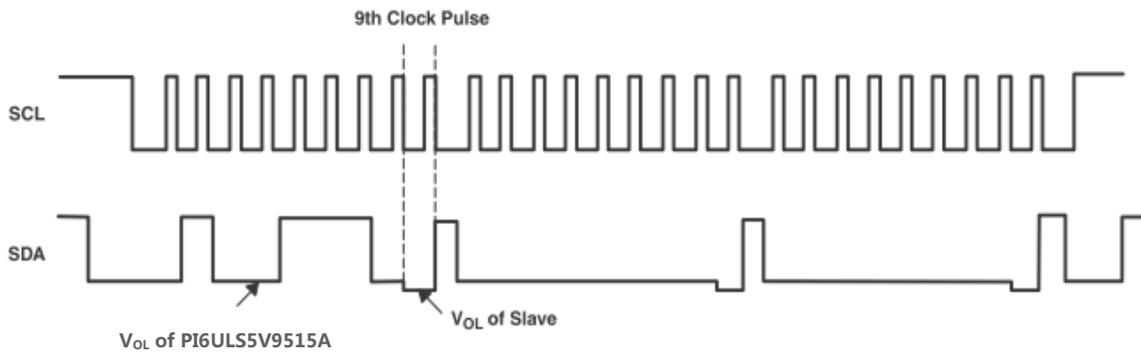


Figure 6: Bus 1 Waveforms

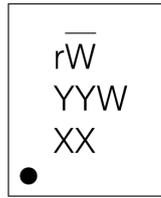
Part Marking

U Package



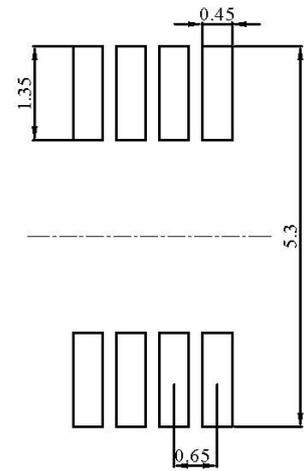
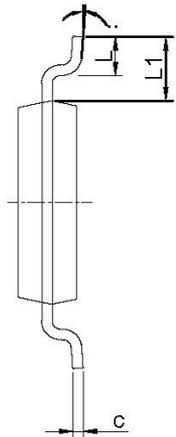
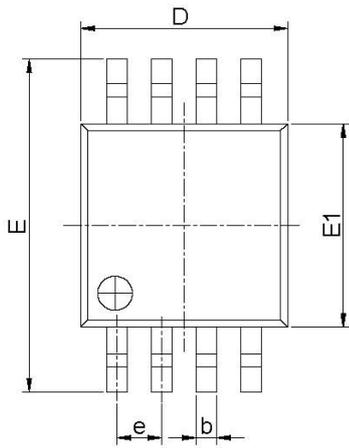
1st Y: Die Rev
2nd Y: Year
W: Workweek
1st X: Assembly Site Code
2nd X: Fab Site Code
Bar above "L" means Fab3 of MGN
Bar above Fab site code means Cu wire

ZE Package



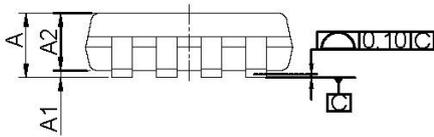
rW: PI6ULS5V9515AZEE
1st Y: Die Rev
2nd Y: Date Code (Year)
W: Date Code (Workweek)
1st X: Assembly Site Code
2nd X: Fab Site Code
Bar above "W" means Fab3 of MGN

Packaging Mechanical
MSOP-8 (U)



PKG DIMENSIONS(MM)		
SYMBOL	Min.	Max.
A	-	1.10
A1	0.00	0.15
A2	0.75	0.95
b	0.22	0.38
c	0.08	0.23
D	2.80	3.20
E	4.65	5.15
E1	2.80	3.20
e	0.65 BSC	
L	0.40	0.80
L1	0.95 REF	
θ	0°	8°

RECOMMENDED LAND PATTERN(unit:mm)



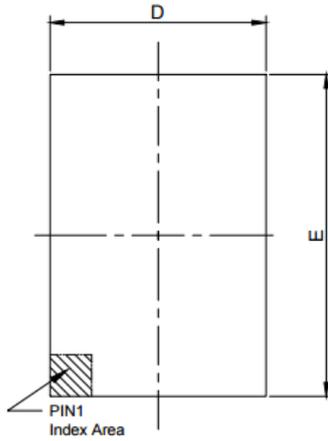
NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. REFER JEDEC MO-187F/AA
3. PACKAGE OUTLINE DIMENSIONS DO NOT INCLUDE MOLD FLASH AND METAL BURR.
4. LAND PATTERN REFERENCE DIODES MSOP-8 PACKAGE INFORMATION.

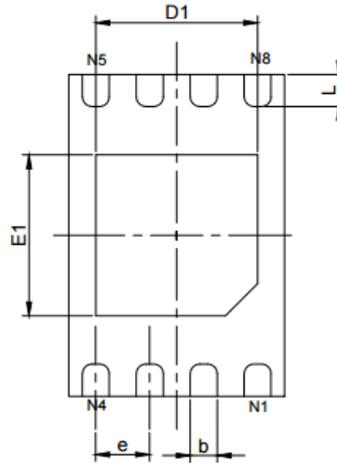
		DATE: 11/04/19
DESCRIPTION: 8-Pin, Mini Small Outline Package, MSOP		
PACKAGE CODE: U (U8)		
DOCUMENT CONTROL #: PD-1261	REVISION: H	

19-1147

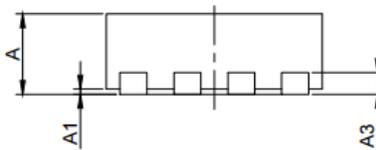
TDFN-8 (ZE)



TOP VIEW



BOTTOM VIEW



SIDE VIEW

PKG. DIMENSIONS(MM)		
SYMBOL	Min	Max
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
D	1.92	2.08
E	2.92	3.07
D1	1.40	1.60
E1	1.40	1.60
k	0.20 MIN	
b	0.20	0.30
e	0.50 TYP	
L	0.22	0.38

Notes:

1. Ref: JEDEC MO-229



DATE: 06/14/13

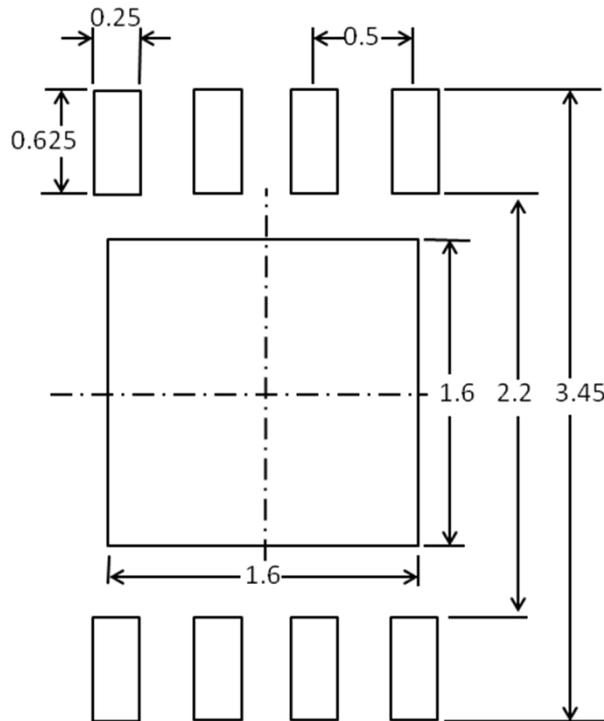
DESCRIPTION: 8-Pin, TDFN, 2X3

PACKAGE CODE: ZE (ZE8)

DOCUMENT CONTROL#: PD-2116

REVISION: --

Recommended Land pattern for TDFN2*3-8L



Note:
All linear dimensions are in millimeters

For latest package info.

please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>

Ordering Information

Part Numbers	Package Code	Package Description
PI6ULS5V9515AUEx	U	8-pin, Mini Small Outline Package (MSOP)
PI6ULS5V9515AZEx	ZE	8-pin, 2x3 (TDFN)

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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